

Digital SiSonic $^{TM}$  Microphone Specification Halogen Free

Knowles Acoustics
1151 Maplewood Drive
Itasca, IL 60143

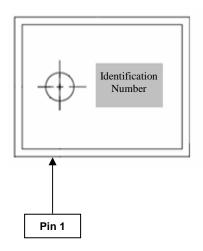




### 1. DESCRIPTION AND APPLICATION

- 1.1 Description
  Digital Surface Mount Silicon Microphone *Halogen Free*
- 1.2 Application
  Hand-held consumer electronic devices

### 2. PART MARKING



### **Identification Number Convention**

S	1	2	3
4	5	6	7

S: Manufacturing Location
"S" – Knowles Electronics Suzhou
Suzhou, China

"No Alpha Character" – Knowles Electronics Itasca Itasca, IL USA

"E" – Engineering Samples

Digits 1 – 7: Job Identification Number

### 3. TEMPERATURE RANGE

3.1 Operating Temperature Range: -40°C to +100°C

3.2 Storage Temperature Range: -40°C to +100°C





## 4. (a) ACOUSTIC & ELECTRICAL SPECIFICATIONS

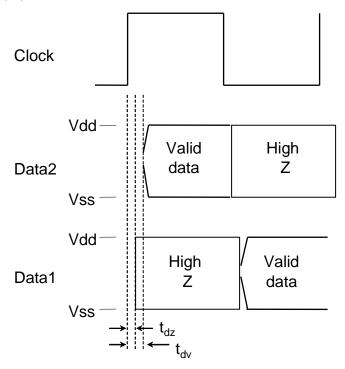
Absolute Maximums	
Supply Voltage, V <sub>dd</sub> to Ground	-0.5, +5.0 VDC
Output Short Circuit	indefinite to either supply rail
ESD Tolerance	4kV

	Symbol	Condition	Limits			Unit
	Symbol	Condition	Min.	Nom.	Max.	
Т	est Conditions	s: $V_{dd} = 1.8V$ , $f_{clock} = 2.4MHz$ , $T_a = 250$	unless otherw	ise noted		
Directivity		Omni-directional				
Sensitivity	S	1kH, 1Pa, ref Full Scale	-30	-26	-22	dB FS
Current Consumption	l <sub>dd</sub>	Output Open Circuit			600	uA
Signal to Noise Ratio	SNR	@ 1kHz (0dB=1V/Pa)		56		dB
Operating Voltage	$V_{dd}$		1.6		3.6	V
Maximum Input Signal		f=1kHz, THD<10%	115			dB
Short Circuit Output Current	I <sub>sc</sub>	Output grounded	1		10	mA
Load Capacitance	C <sub>out</sub>	Maxim load capacitance			100	pF
Standby Current (sleep mode)	I	fclk < 1kHz			50	uA
Lid to Ground Resistance					100	Ω
Data Format		½ Cycle PDM				
Clock Frequency	f <sub>clock</sub>		1.0		3.25	MHz
Clock Duty Cycle			40		60	%
Logic Low	V <sub>OL</sub>		-0.3	V <sub>ss</sub>	0.35x V <sub>dd</sub>	V
Logic High	V <sub>OH</sub>		0.65x V <sub>dd</sub>	$V_{dd}$	V <sub>dd</sub> +0.3	V
Delay time for valid data	t <sub>dv</sub>		20		40	ns
Delay time for High Z	t <sub>dz</sub>		0		15	ns

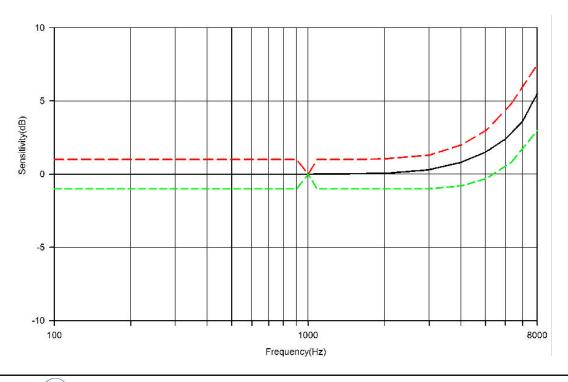




## 4. (b) TIMING DIAGRAM



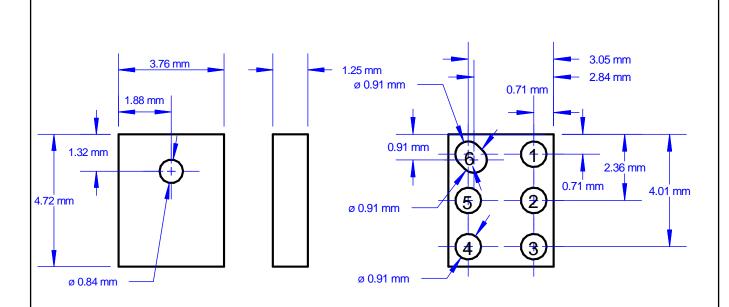
## 5. FREQUENCY RESPONSE CURVE







## 6. MECHANICAL SPECIFICATIONS



Pin Output			
Pin # Function			
1	Ground		
2	Left/Right		
3	Ground		
4	Clock		
5	Data		
6	Power (Vdd)		

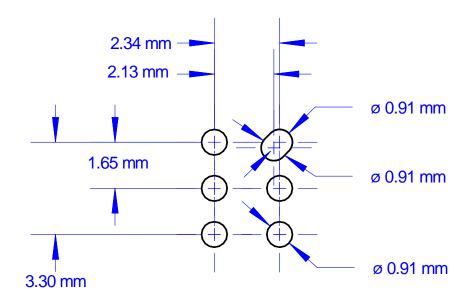
<u>ltem</u>	<u>Dim.</u>	<u>Tol. (+/-)</u>	<u>Units</u>
Height	1.25	0.10	mm
Length	4.72	0.10	mm
Width	3.76	0.10	mm
Short Edge to C.L. Port	1.32	0.25	mm
Long Edge to C.L. Port	1.88	0.25	mm
Coplanarity	<0.1	mm	
Acoustic Seal I.D. (typical)	1.55	mm	
Weight	0.07	grams	

Note: (Tolerance +/-0.15mm unless otherwise specified)





### 7. RECOMMENDED CUSTOMER LAND PATTERN

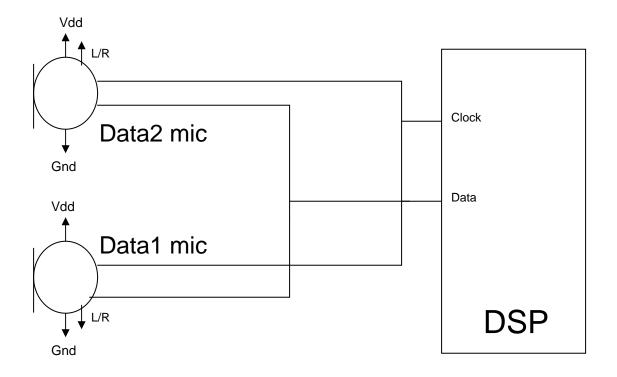


# 8. RECOMMENDED SOLDER STENCIL PATTERN N/A





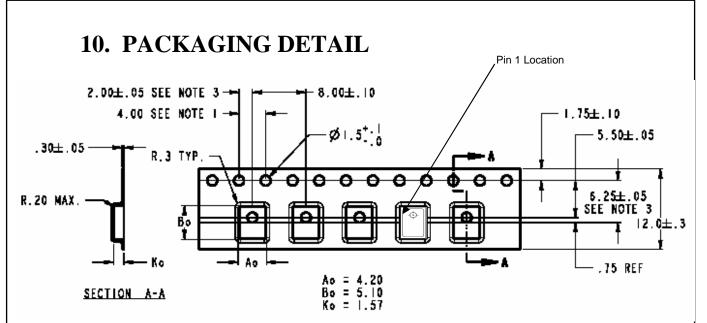
## 9. RECOMMENDED INTERFACE CIRCUIT



Label:	L/R:	Drives data after:	High-Z after:
Data2	High	Rising clock edge	Falling clock edge
Data1	Low	Falling clock edge	Rising clock edge







#### NOTES:

- 1. 10 SPROCKET HOLE PITCH CUMULATIVE TOLERANCE  $\pm 0.2$ . 2. CAMBER IN COMPLIANCE WITH EIA 481. 3. POCKET POSITION RELATIVE TO SPROCKET HOLE MEASURED AS TRUE POSITION OF POCKET.

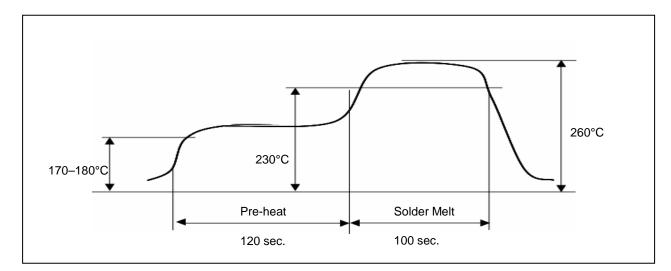
Model Number	<u>Suffix</u>	<u>Reel</u> <u>Diameter</u>	Quantity per Reel
SPM0205HD4H	-2	7"	1,200
SPM0205HD4H	-6	13"	4,800

Tape & Reel	Available in 13" and 7" diameter.
Empty Units	No consecutive empty pockets; No more than 3 empty pockets per reel. (Does not include empty pockets for leader/follower)





### 11. MAXIMUM SOLDER REFLOW PROFILE



<u>Stage</u>	<u>Temperature Profile</u>	<u>Time (maximum)</u>	
Pre-heat	170 ~ 180 C	120 sec.	
Solder Melt	Above 230 C	100 sec.	
Peak	260 C maximum	30 sec.	

### Notes:

- 1. <u>Do not pull a vacuum</u> over the port hole of the microphone. Pulling a vacuum over the port hole can damage the device.
- 2. <u>Do not board wash</u> after the reflow process. Board washing and cleaning agents can damage the device. Do not expose to ultrasonic processing or cleaning.
- 3. Number of Reflow = recommend no more than 3 cycles.

### 12. ADDITIONAL NOTES

- (A) Packaging (reference SiSonic\_Packaging\_Spec.pdf)
- (B) Shelf life: Twelve (12) months when devices are to be stored in factory supplied, unopened ESD moisture sensitive bag under maximum environmental conditions of 30°C, 70% R.H.
- (C) Exposure: Devices should not be exposed to high humidity, high temperature environment. MSL (moisture sensitivity level) Class 2A.
- (D) Out of bag: Maximum of 90 days out of ESD moisture sensitive bag, assuming maximum conditions of 30°C/70% R.H.





## 13. RELIABILITY SPECIFICATIONS

Note: After test conditions are performed, the sensitivity of the microphone shall not deviate more than 3dB from its initial value.

Test	Description
Thermal Shock	100 cycles of air-air thermal shock from -40C to +125C with 15min soaks. (ICE 68-2-4)
High Temperature Storage	+105C environment for 1,000 hours. (IEC 68-2-2 Test Ba)
Low Temperature Storage	-40C environment for 1,000 hours. (IEC 68-2-2 Test Aa)
High Temperature Bias	+105C environment while under bias for 1,000 hours. (IEC 68-2-2 Test Ba)
Low Temperature Bias	-40C environment while under bias for 1,000 hours. (IEC 68-2-2 Test Aa)
Temperature / Humidity Bias	+85C/85% RH environment while under bias for 1,000 hours. (JESD22-A101A-B)
Vibration	4 cycles lasting 12 minutes from 20 to 2,000Hz in X, Y, and Z direction with a peak acceleration of 20g. (MIL 883E, Method 2007.2, A)
Electrostatic Discharge	3 discharges at +/- 8kV direct contact to the lid when unit is grounded (IEC 1000-4-2) and 3 discharges at +/- 2kV direct contact to the I/O pins (MIL 883E, Method 3015.7)
Reflow	5 reflow cycles with peak temperature of 260C.
Mechanical Shock	3 pulses of 5,000g in the X, Y, and Z direction. (IEC 68-2-27, Test Ea)





### 14. SPECIFICATION REVISIONS

Revision	Detailed Specification Changes	Date
А	Specification Release	06-30-2008

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